

SN54AHCT158, SN74AHCT158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MUXES

SCLS348J – MAY 1996 – REVISED JULY 2003

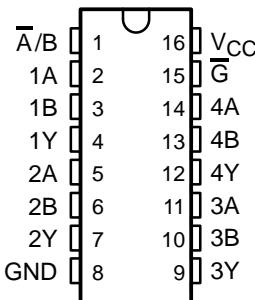
- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information

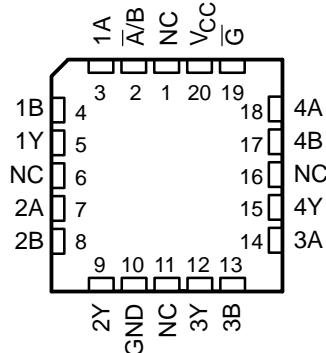
These quadruple 2-line to 1-line data selectors/multiplexers are designed for 4.5-V to 5.5-V V_{CC} operation.

The 'AHCT158 devices feature a common strobe (\bar{G}) input. When the strobe is high, all outputs are high. When the strobe is low, a 4-bit word is selected from one of two sources and is routed to the four outputs. The devices provide inverted data.

SN54AHCT158 . . . J OR W PACKAGE
SN74AHCT158 . . . D, DB, DGV, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54AHCT158 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	SN74AHCT158N	SN74AHCT158N
	SOIC – D	Tube	SN74AHCT158D	AHCT158
		Tape and reel	SN74AHCT158DR	
	SOP – NS	Tape and reel	SN74AHCT158NSR	AHCT158
	SSOP – DB	Tape and reel	SN74AHCT158DBR	HB158
	TSSOP – PW	Tube	SN74AHCT158PW	HB158
		Tape and reel	SN74AHCT158PWR	
–55°C to 125°C	TVSOP – DGV	Tape and reel	SN74AHCT158DGVR	HB158
	CDIP – J	Tube	SNJ54AHCT158J	SNJ54AHCT158J
	CFP – W	Tube	SNJ54AHCT158W	SNJ54AHCT158W
	LCCC – FK	Tube	SNJ54AHCT158K	SNJ54AHCT158FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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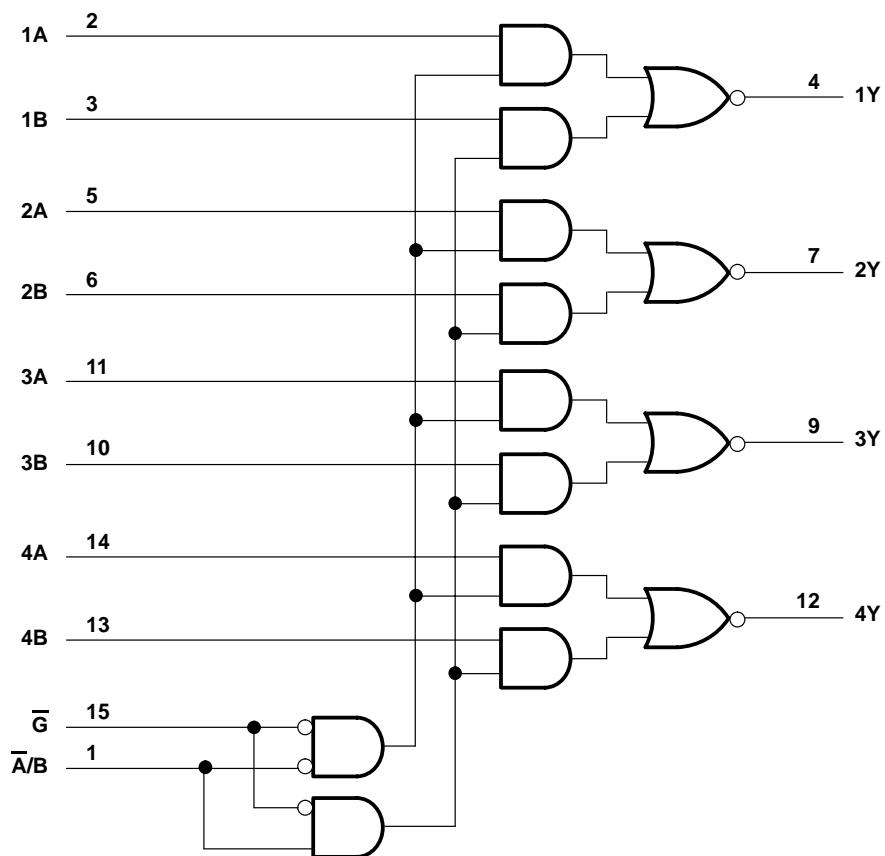
SN54AHCT158, SN74AHCT158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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FUNCTION TABLE (each data selector/multiplexer)

INPUTS				OUTPUT
\bar{G}	\bar{A}/B	A	B	Y
H	X	X	X	H
L	L	L	X	H
L	L	H	X	L
L	H	X	L	H
L	H	X	H	L

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, N, NS, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V	
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V	
Output voltage range, V_O (see Note 1)	–0.5 V to V_{CC} + 0.5 V	
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA	
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA	
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA	
Continuous current through V_{CC} or GND	±50 mA	
Package thermal impedance, θ_{JA} (see Note 2): D package	73°C/W	
DB package	82°C/W	
DGV package	120°C/W	
N package	67°C/W	
NS package	64°C/W	
PW package	108°C/W	
Storage temperature range, T_{STG}	–65°C to 150°C	

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		SN54AHCT158		SN74AHCT158		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	5.5	0	5.5	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–8		–8	mA
I_{OL}	Low-level output current		8		8	mA
$\Delta t/\Delta v$	Input transition rise or fall time		20		20	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54AHCT158, SN74AHCT158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MUXES

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AHCT158		SN74AHCT158		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 µA	4.5 V	4.4	4.5		4.4		4.4		V
	I _{OH} = -8 mA		3.94			3.8		3.8		
V _{OL}	I _{OL} = 50 µA	4.5 V		0.1		0.1		0.1		V
	I _{OL} = 8 mA			0.36		0.44		0.44		
I _I	V _I = 5.5 V or GND	0 V to 5.5 V		±0.1		±1*		±1	µA	
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V		2		20		20	µA	
ΔI _{CC} †	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V		1.35		1.5		1.5	mA	
C _i	V _I = V _{CC} or GND	5 V	2	10				10	pF	

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

† This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54AHCT158		SN74AHCT158		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B	Y	C _L = 15 pF	4.1**	6.4**		1**	7.5**	1	7.5	ns
t _{PHL}				4.1**	6.4**		1**	7.5**	1	7.5	
t _{PLH}	A/B	Y	C _L = 15 pF	5.3**	8.1**		1**	9.5**	1	9.5	ns
t _{PHL}				5.3**	8.1**		1**	9.5**	1	9.5	
t _{PLH}	G	Y	C _L = 15 pF	5.6**	8.6**		1**	10**	1	10	ns
t _{PHL}				5.6**	8.6**		1**	10**	1	10	
t _{PLH}	A or B	Y	C _L = 50 pF	5.6	8.7		1	10.8	1	9.8	ns
t _{PHL}				5.6	8.7		1	10.8	1	9.8	
t _{PLH}	A/B	Y	C _L = 50 pF	6.8	10.4		1	13.2	1	12	ns
t _{PHL}				6.8	10.4		1	13.2	1	12	
t _{PLH}	G	Y	C _L = 50 pF	7.1	11		1	13.5	1	12	ns
t _{PHL}				7.1	11		1	13.5	1	12	

** On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

PARAMETER	SN74AHCT158			UNIT
	MIN	TYP	MAX	
V _{OL(P)} Quiet output, maximum dynamic V _{OL}			0.8	V
V _{OL(V)} Quiet output, minimum dynamic V _{OL}			-0.8	V
V _{OH(V)} Quiet output, minimum dynamic V _{OH}			4.8	V
V _{IH(D)} High-level dynamic input voltage		2		V
V _{IL(D)} Low-level dynamic input voltage			0.8	V

NOTE 4: Characteristics are for surface-mount packages only.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.

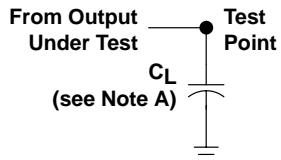


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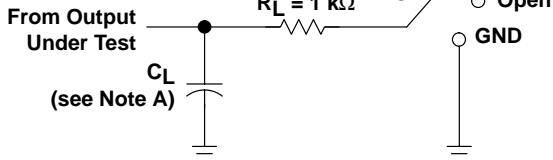
operating characteristics, $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load, f = 1 MHz	11	pF

PARAMETER MEASUREMENT INFORMATION

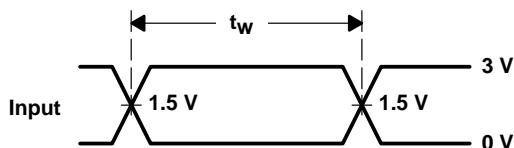


LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS

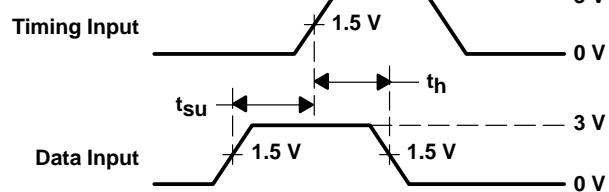


LOAD CIRCUIT FOR
3-STATE AND OPEN-DRAIN OUTPUTS

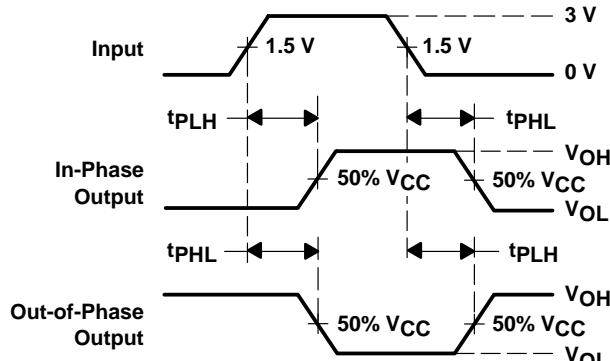
TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _{CC}
t _{PHZ} /t _{PZH}	GND
Open Drain	V _{CC}



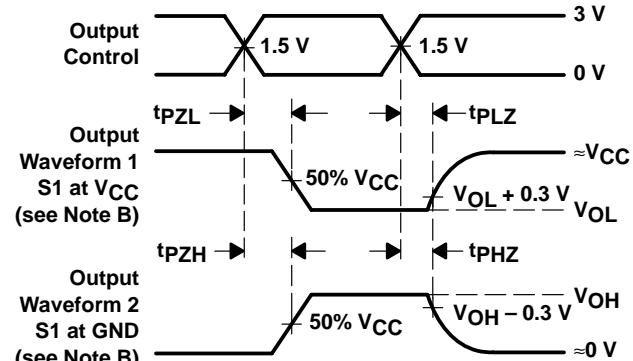
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, $Z_O = 50 \Omega$, $t_f \leq 3$ ns, $t_r \leq 3$ ns.
 D. The outputs are measured one at a time with one input transition per measurement.
 E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74AHCT158D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74AHCT158DBLE	OBsolete	SSOP	DB	16		TBD	Call TI	Call TI	Samples Not Available
SN74AHCT158DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74AHCT158DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74AHCT158PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74AHCT158PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74AHCT158PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74AHCT158PWLE	OBsolete	TSSOP	PW	16		TBD	Call TI	Call TI	Samples Not Available
SN74AHCT158PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74AHCT158PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74AHCT158PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.



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PACKAGE OPTION ADDENDUM

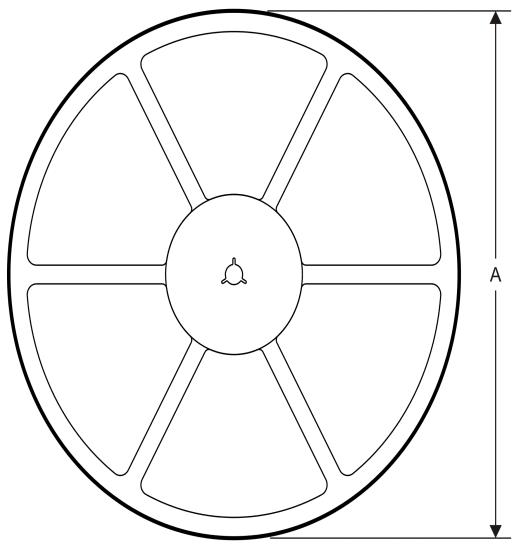
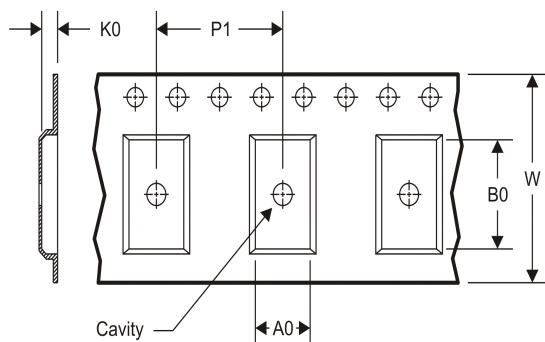
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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

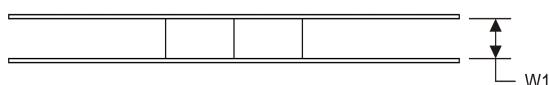
(³) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers


TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT158PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

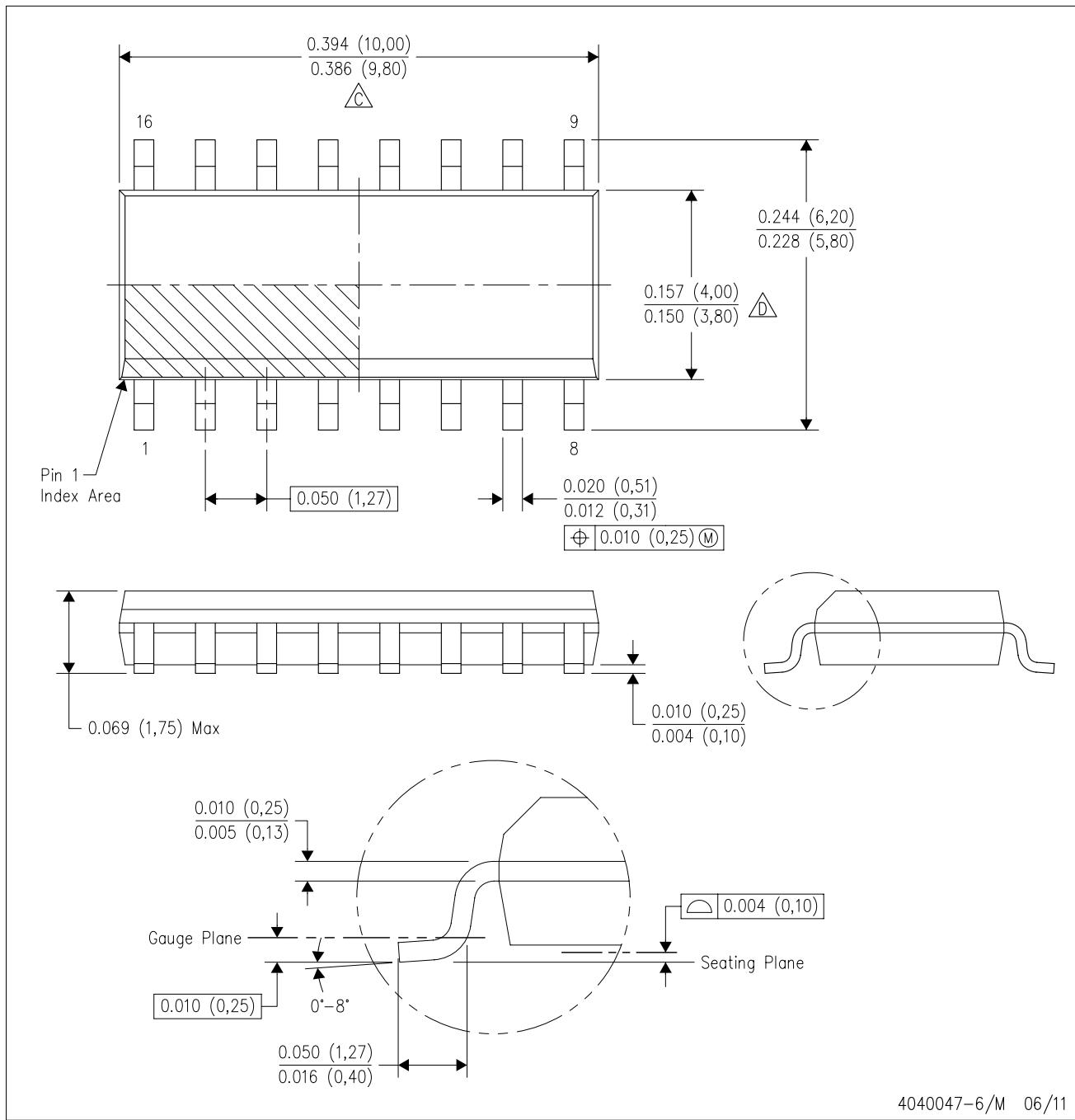
TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT158PWR	TSSOP	PW	16	2000	367.0	367.0	35.0

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

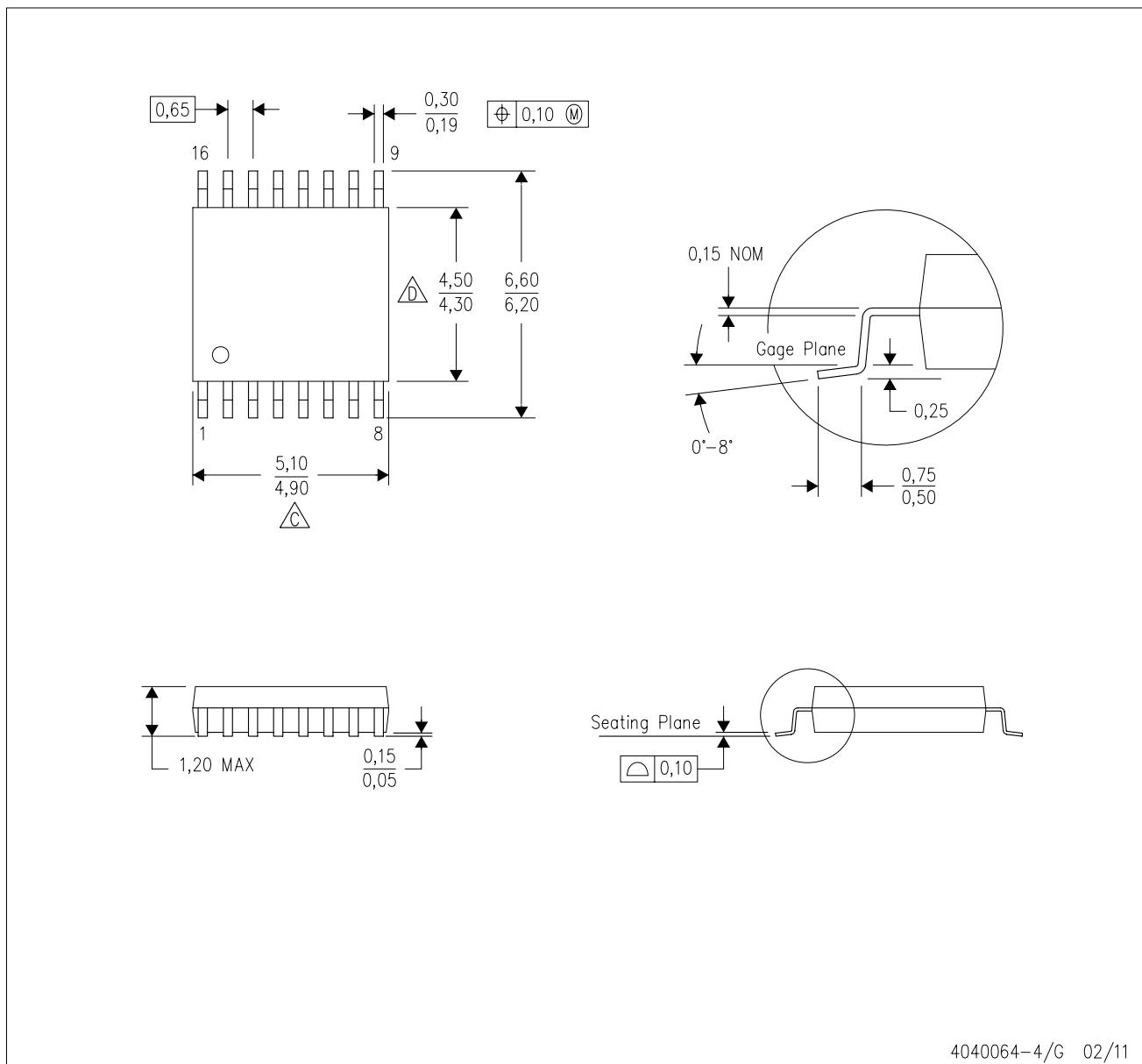
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.

D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.

E. Reference JEDEC MS-012 variation AC.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040064-4/G 02/11

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

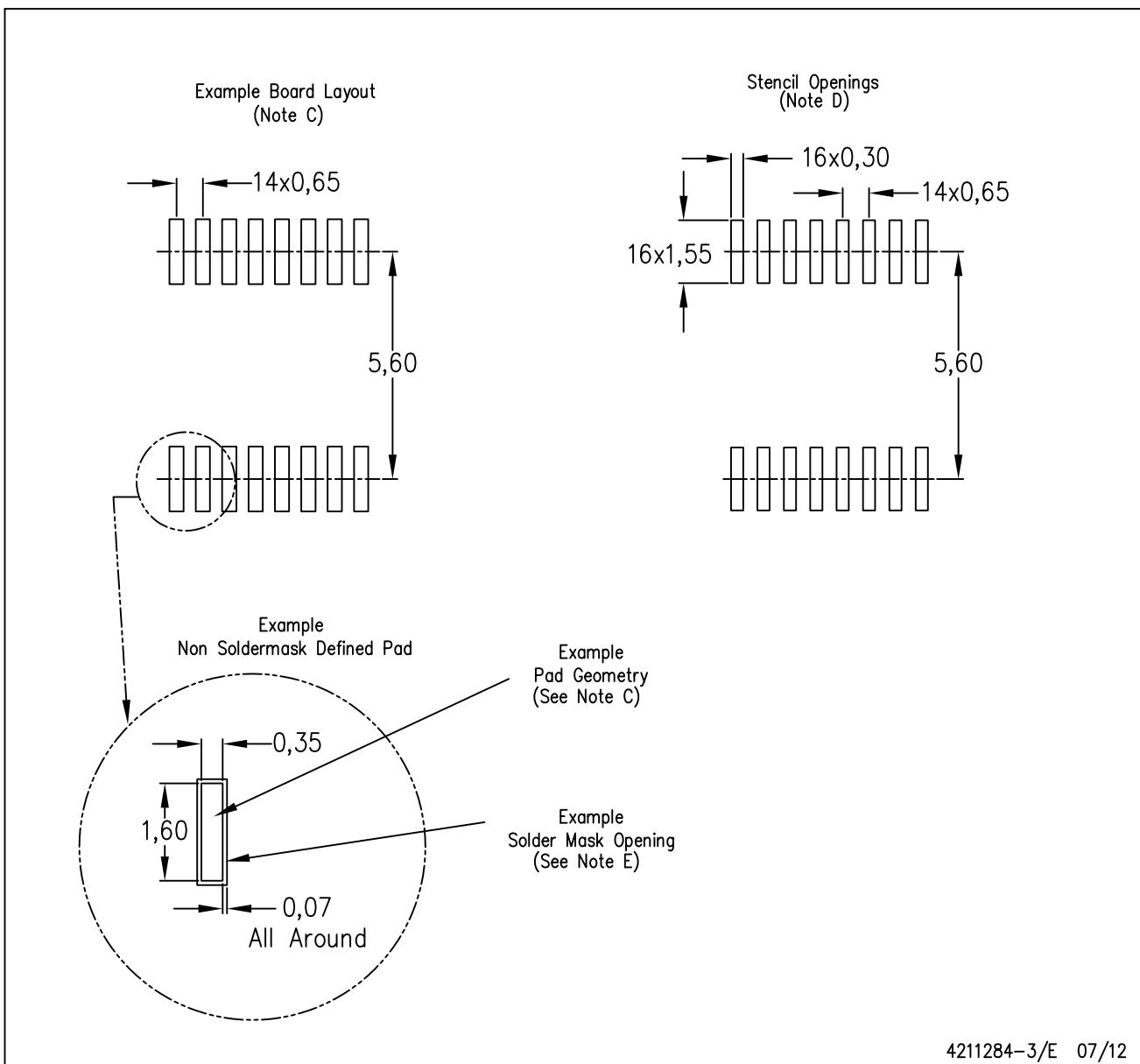
△C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

△D Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



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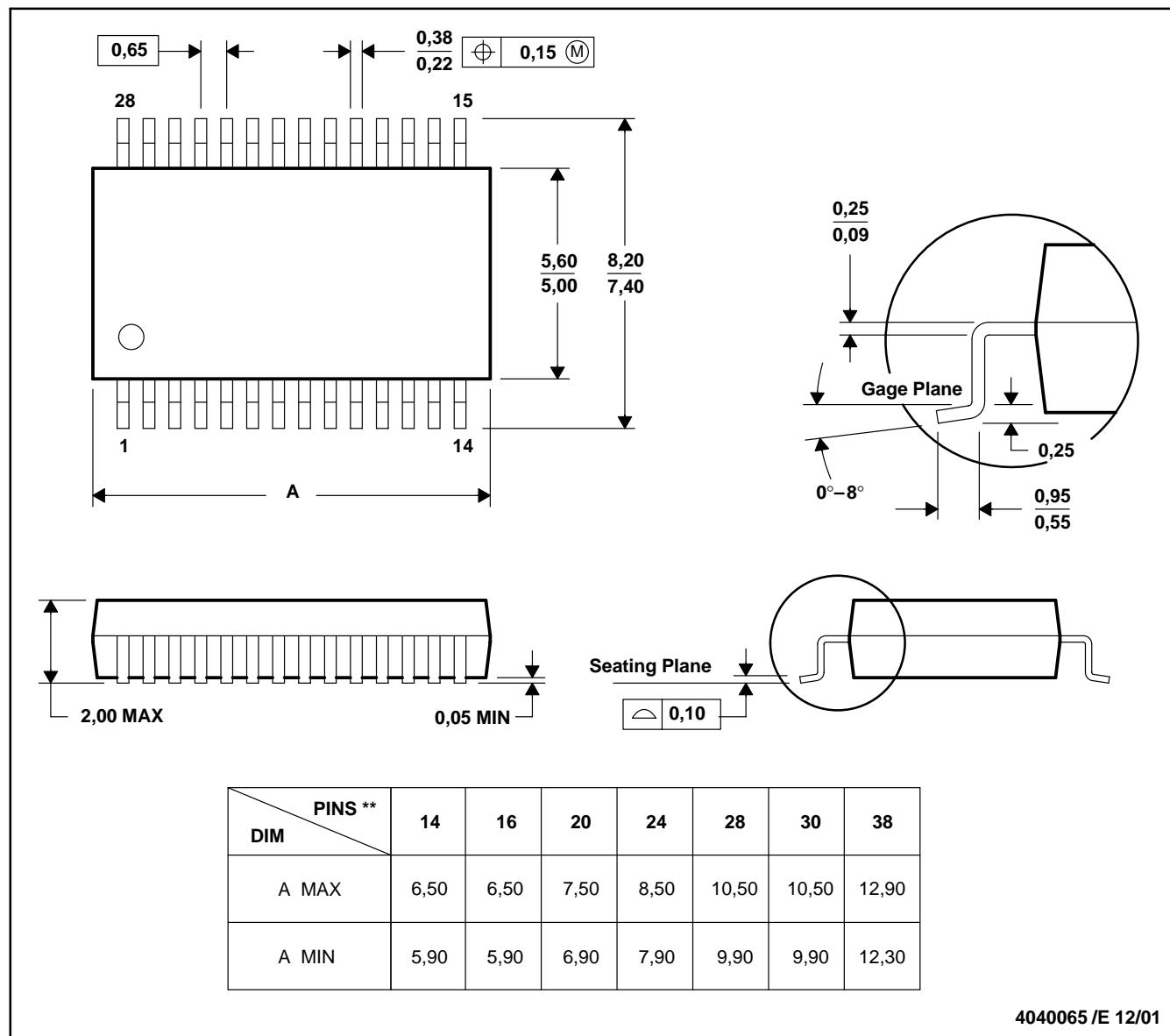
NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate designs.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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